

**METHOD FOR BONDING CONSTRUCTION MEMBER AND ADHESIVE SHEET TO BE USED THEREFOR**

Patent Number: JP5340058  
Publication date: 1993-12-21  
Inventor(s): SANO KENJI; others: 03  
Applicant(s):: NITTO DENKO CORP  
Requested Patent: ☐ JP5340058  
Application Number: JP19920171920 19920605  
Priority Number(s):  
IPC Classification: E04F13/08 ; C09J5/06 ; C09J7/00  
EC Classification:  
Equivalents:

**Abstract**

**PURPOSE:**To shorten the bonding time by interposing a heat sensitive adhesive sheet, in which the induction heating material is embedded, between the surfaces to be bonded to each other, and melting the heat sensitive adhesive sheet by the high frequency induction heating of this induction heating material.  
**CONSTITUTION:**The eddy current is induced by the high frequency magnetic flux, and on both surfaces of a metal foil or a metal net, which is heated by the joule heating, the heat sensitive adhesive agent is formed into a sheet-shape to obtain the heat sensitive adhesive sheet. Next, a board is fitted to the wall base surface through the heat sensitive adhesive sheet, and under the condition that this board is pressed, the high frequency magnetic field is applied by a high frequency magnetic field generator from the surface side of the board to heat the induction heating material and melt the sheet, and the board is thereby attached to the wall base surface. The contact area of the adhesive agent is increased by setting the dynamic shearing storage elastic modulus of the heat sensitive adhesive agent at the time of bonding-heating at  $3 \times 10^{-6}$  dyn/cm<sup>2</sup> or less; and the cold creep is prevented by setting the dynamic shearing storage elastic modulus of the heat sensitive adhesive material at 20 deg.C at  $3 \times 10^{-6}$  dyn/cm<sup>2</sup> or more. Consequently, the bonding in a short time is enabled.

Data supplied from the esp@cenet database - I2